

Title (en)
Ceramic substrate having a metal circuit

Title (de)
Keramisches Substrat mit einer metallischen Schaltung

Title (fr)
Substrat céramique avec un circuit métallique

Publication
EP 0915512 A3 20000517 (EN)

Application
EP 98119746 A 19981021

Priority
JP 30563497 A 19971107

Abstract (en)
[origin: EP0915512A2] A substrate having a metal circuit and/or a heat-radiating metal plate formed on a ceramic substrate, wherein the metal circuit and/or the heat-radiating metal plate comprise the following first metal-second metal bonded product (except for a combination of the same kinds of metals of the first metal and the second metal) and/or the following first metal-third metal-second metal bonded product, and the first metal is bonded to the ceramic substrate; first metal: a metal selected from the group consisting of aluminum (Al), lead (Pb), platinum (Pt) and an alloy containing at least one of these metal components, second metal: a metal selected from the group consisting of copper (Cu), silver (Ag), gold (Au), aluminum (Al) and an alloy containing at least one of these metal components, and third metal: a metal selected from the group consisting of titanium (Ti), nickel (Ni), Zirconium (Zr), molybdenum (Mo), tungsten (W) and an alloy containing at least one of these metal components.

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H01L 23/498; **H01L 21/48**; **H01L 23/373**

IPC 8 full level
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CPC (source: EP KR US)
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